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Nota di contenuto	Contents; English - Abstracts & keywords; French - Abstracts & keywords; German - Abstracts & keywords; Contributors; Editorial; High frequency PCB base materials - a comparison of thermomechanical properties; High performance epoxy copper clad laminate; High-performance substrate from new epoxy resin and enhanced copper foil; An innovative "Chemical Via" process for the production of high density interconnect printed circuit boards; An introduction to high performance laminates and the importance of using optimised chemical processes in PCB fabrication A novel method for sequentially-building multi-layer circuits using LCP laminates, cap-layers and bond plys PCB drillability: a material science approach to resin development; What share of the global upturn can Europe retain?; Internet commentary; Book reviews; Intellect commentary; Company profile; Association news; New products; Industry news; Exhibitions and conferences; Appointments; International diary
Sommario/riassunto	There is increasing customer demand for materials with low dissipation factors for reduced loss along the traces and low dielectric constants for higher signal propagation speeds. High performance epoxies such as Nelco's N4000- 13, Isola's FR408 and General Electric's GETEK

(similar to Matsushita's MEGTRON) have become essential for boards operating in the higher frequency range. For applications at the highest frequencies material choices are very limited. These materials, tailored for high frequency use, have disadvantages - either with their thermomechanical properties or with their process
